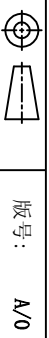


PCB LAYOUT

- Note:
1. Material:
    - 1.1 Housing: High temperature thermoplastic with g.f., UL94V-0
    - 1.2 Contact: copper alloy, t=0.15mm
    - 1.3 Shell: copper alloy&SUS
  2. Specification:
    - 2.1 Current rating: 1 A Max.
    - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
    - 2.3 Contact resistance: 30 mΩ Max.
    - 2.4 Insulation resistance: 100 MΩ Min.
    - 2.5 Total mating force: 3.57 Kgf Max.
    - 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
    - 2.7 Temperature range: -30°C~80°C

尺寸	允许公差	图 纸 类 型			
X.	±0.50	产品工程图			
.X	±0.20				
.XX	±0.10				
.XXX	±0.03	设计	zhuyin	2011.07.21	产品料号
角度	±1.00°	审核			视图

图纸名称: MICRO 5P/F B 反向牛角内DIP 0.6(7.7\*5.3)



版本号: A/0

A/0